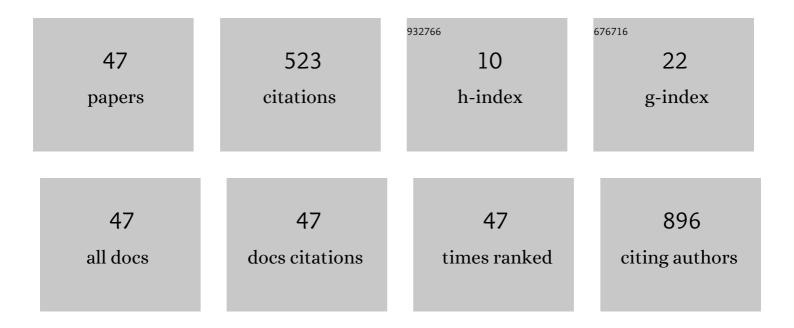
Elke Kraker

List of Publications by Year in descending order

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FIRE KDARED

#	Article	IF	CITATIONS
1	An Allâ€Printed Ferroelectric Active Matrix Sensor Network Based on Only Five Functional Materials Forming a Touchless Control Interface. Advanced Materials, 2011, 23, 2069-2074.	11.1	215
2	Integrated organic electronic based optochemical sensors using polarization filters. Applied Physics Letters, 2008, 92, .	1.5	52
3	Wet chemical deposited ITO coatings on flexible substrates for organic photodiodes. Thin Solid Films, 2009, 518, 1164-1169.	0.8	42
4	Diffusion of Ag into Organic Semiconducting Materials: A Combined Analytical Study Using Transmission Electron Microscopy and X-ray Reflectivity. ACS Applied Materials & Interfaces, 2012, 4, 5608-5612.	4.0	22
5	An optical sensor array on a flexible substrate with integrated organic opto-electric devices. Procedia Engineering, 2010, 5, 1005-1008.	1.2	16
6	Integrated fluorescence sensor based on ringâ€ s haped organic photodiodes. Physica Status Solidi - Rapid Research Letters, 2010, 4, 157-159.	1.2	14
7	Organic photodiodes on flexible substrates. Thin Solid Films, 2009, 518, 1214-1217.	0.8	12
8	Enabling luminescence decay time-based sensing using integrated organic photodiodes. Analytical and Bioanalytical Chemistry, 2013, 405, 5975-5982.	1.9	12
9	Integrated waveguide sensor utilizing organic photodiodes. Physica Status Solidi - Rapid Research Letters, 2011, 5, 344-346.	1.2	11
10	Validation methodology to analyze the temperature-dependent heat path of a 4-chip LED module using a finite volume simulation. Microelectronics Reliability, 2017, 79, 462-472.	0.9	10
11	Organic optoelectronic device fabrication using standard UV photolithography. Physica Status Solidi - Rapid Research Letters, 2008, 2, 16-18.	1.2	9
12	Thermal transient measurement and modelling of a power cycled flip-chip LED module. Microelectronics Reliability, 2018, 81, 373-380.	0.9	9
13	Parameter driven monitoring for a flip-chip LED module under power cycling condition. Microelectronics Reliability, 2018, 82, 84-89.	0.9	8
14	Metal Oxide Nanowires for Gas Sensor Applications. BHM-Zeitschrift Fuer Rohstoffe Geotechnik Metallurgie Werkstoffe Maschinen-Und Anlagentechnik, 2014, 159, 385-389.	0.4	7
15	Reliability and failure analysis of solder joints in flip chip LEDs via thermal impedance characterisation. Microelectronics Reliability, 2017, 76-77, 601-605.	0.9	7
16	Structure and morphology of an organic/inorganic multilayer stack: An x-ray reflectivity study. Journal of Applied Physics, 2011, 110, .	1.1	6
17	Filter-free integrated sensor array based on luminescence and absorbance measurements using ring-shaped organic photodiodes. Analytical and Bioanalytical Chemistry, 2012, 404, 2841-2849.	1.9	6
18	Micromechanics-based damage model for liquid-assisted healing. International Journal of Damage Mechanics, 2021, 30, 123-144.	2.4	6

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19	Analysis of Sn-Bi Solders: X-ray Micro Computed Tomography Imaging and Microstructure Characterization in Relation to Properties and Liquid Phase Healing Potential. Materials, 2021, 14, 153.	1.3	6
20	Development of printed ITO coatings on PET and PEN foil for flexible organic photodiodes. , 2008, , .		5
21	Structure Function Analysis of Temperature-Dependent Thermal Properties of Nm-Thin Nb2O5. Energies, 2019, 12, 610.	1.6	5
22	Thermal Characterization of Nm-thin Nb2O5 by Applying Thermal Impedance Methods to Time Domain Thermoreflectance Measurements. , 2018, , .		4
23	Temperature Sensitive Electrical Parameter Sensing Unit for Early Failure Detection. , 2019, , .		4
24	Effect of solder joint size and composition on liquid-assisted healing. Microelectronics Reliability, 2021, 119, 114066.	0.9	4
25	Simulation and experimental characterization of microporosity during solidification in Sn-Bi alloys. Materials and Design, 2021, 212, 110258.	3.3	4
26	Investigation of the temperature-dependent heat path of an LED module by thermal simulation and design of experiments. , 2016, , .		3
27	Numerical study on local effects of composition and geometry in self-healing solders. , 2019, , .		3
28	Waveguide-integrated SPR sensing on an all-organic platform. Proceedings of SPIE, 2011, , .	0.8	2
29	ORGANIC PHOTODIODES ON PRINTED ITO COATINGS. International Journal of High Speed Electronics and Systems, 2011, 20, 787-799.	0.3	2
30	Integrated organic optical sensor arrays based on ring-shaped organic photodiodes. , 2011, , .		2
31	All printed touchless human-machine interface based on only five functional materials. , 2012, , .		2
32	Screen-printed polymer waveguides for integrated optics. Applied Physics B: Lasers and Optics, 2013, 111, 647-650.	1.1	2
33	Reliability assessment of contact wires in LED-devices using in situ X-ray computed tomography and thermo-mechanical simulations. , 2014, , .		2
34	Healing solders: A numerical investigation of damage-healing experiments. , 2020, , .		2
35	TSEP-Sensitivity Study to Analyze the Soldering Process of a Power Diode. , 2020, , .		2
36	Probabilistic Approach for Temperature Driven Fatigue Lifetime Data Analysis to Improve Prognostics and Health Management of LED Packages. , 2020, , .		2

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37	Optochemical sensor based on screenprinted fluorescent sensorspots surrounded by organic photodiodes for multianalyte detection. Proceedings of SPIE, 2010, , .	0.8	1
38	Integrated waveguide sensor platform utilizing organic photodiodes. , 2012, , .		1
39	Accelerated thermo-mechanical test method for LED modules. , 2016, , .		1
40	Novel integrated organic sensor system for the detection of oxygen and pH. , 2008, , .		0
41	Performance and parameter variation of flexible organic thin film transistors in multicomponent organic sensors. Proceedings of SPIE, 2010, , .	0.8	0
42	Organic photodiodes as monolithically integrated detectors in micro-optical systems. , 2011, , .		0
43	Opto-chemical sensors based on integrated ring-shaped organic photodiodes: progress and applications. Proceedings of SPIE, 2012, , .	0.8	0
44	Study on the temperature-dependent thermal resistance matrix of a multi-chip LED-matrix. , 2017, , .		0
45	A Close Look on Voids in Solder Joints. , 2018, , .		0
46	Lap shear test for solder materials: Local stress states and their effect on deformation and damage. Microelectronics Reliability, 2020, 109, 113655.	0.9	0
47	Modelling of Void Collapse with Molecular Dynamics in Pure Sn. Proceedings (mdpi), 2020, 56, .	0.2	0